

## **AMENDMENTS TO THE SPECIFICATION**

**Please amend paragraph [0028], as follows:**

The top ring 30 is coupled to a top ring shaft 32, which is connected to a motor (not shown) and a lifting/lowering cylinder (not shown). Thus, the top ring 30 is rotatable about the top ring shaft 32 by the motor and lifted and lowered by the lifting/lowering cylinder, as shown by arrows in FIG. 1. The top ring 30 has an elastic pad 34, which is made of polyurethane or the like, on a lower surface of the top ring 30. The semiconductor wafer W to be polished is attracted under vacuum and held on a lower surface of the elastic pad 34, which is a holding surface.

**Please amend paragraph [0029], as follows:**

With such an arrangement, the top ring 30 can press the semiconductor wafer W, which is held on the lower surface of the top ring 30, against the polishing pad 10 under a desired pressure while being rotated. The top ring 30 has a guide ring 36 disposed around a lower outer circumferential edge thereof and around the holding surface thereof for retaining the semiconductor substrate W against dislodgement from the top ring 30.

**Please amend paragraph [0032], as follows:**

FIG. 2 is a schematic view showing the film thickness measuring device 150. As shown in FIG. 2, the film thickness measuring device 150 has a light source 154 for applying light, having a wavelength in a predetermined range, to the surface of the semiconductor wafer W held by the top ring, a spectroscope 155 for separating light reflected from the surface of the semiconductor wafer W, and a charge coupled device array (CCD array) 156 for capturing light separated by the spectroscope 155. The light source 154 and the CCD array 156 in the film thickness measuring device 150 are connected to a controller 160 by a cable 158, which extends through the polishing table 20, a polishing table shaft 20a, and a rotary connector 159 mounted on an end of the polishing table shaft 20a (see FIG. 1). The controller 160 is connected to an output device such as a display unit 162. As is clear from the above as well as Figs. 1-3, the sum of the radial lengths of the light source and the spectroscope is larger than a radius of the holding surface of the top ring.